

A1  
said multilayer wiring film having a first surface in contact with said metal base plate,  
said first surface having a plurality of first metal pads in a region of said first surface exposed by  
said opening in said metal base plate.

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**Please add the following new claims 42-45:**

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42. (New) The semiconductor package board according to claim 1, wherein said first  
metal pads comprise a surface which is not in contact with said multilayer wiring film, said  
surface being coplanar with said multilayer wiring film.

A2  
43. (New) The semiconductor package board according to claim 1, wherein said first  
metal pads comprise a surface which is not in contact with said multilayer wiring film, said  
surface being recessed toward said first surface of said multilayer wiring film.

44. (New) The semiconductor package board according to claim 1, wherein the surface  
of said first metal pads is recessed from the surface of said multilayer wiring film.

45. (New) A semiconductor package board comprising:  
a metal base plate having an opening; and  
a multilayer wiring film formed on said metal base plate, said multilayer wiring film  
having a first surface in contact with said metal base plate and mounting thereon a plurality of  
first metal pads within a region exposed from said opening of said metal base plate, wherein  
surface of the first metal pads is recessed from the surface of the multilayer wiring film.

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